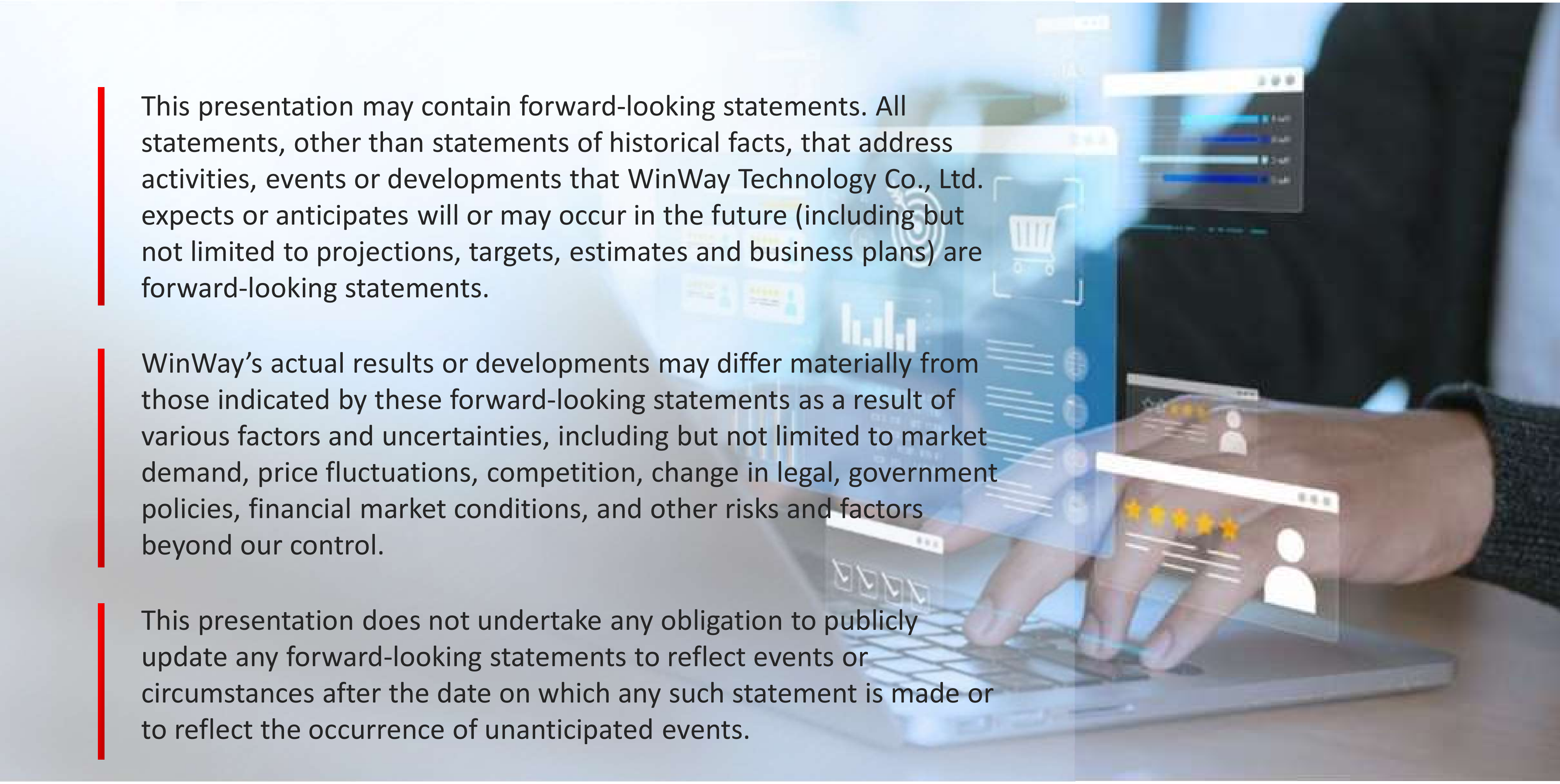
TWSE: 6515

Investor Presentation

2024.09.03

Safe Harbor Notice



This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

Kaohsiung Headquarter

Hsinchu Branch Office

Founded

2001 / 4 / 10

Business Operation

Design, manufacture, sale and service of test interface products

Chairman & CEO

Mark Wang

Capital Stock

NTD 347,691,200

Employees

919

Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist.
Kaohsiung City, Taiwan

Agenda

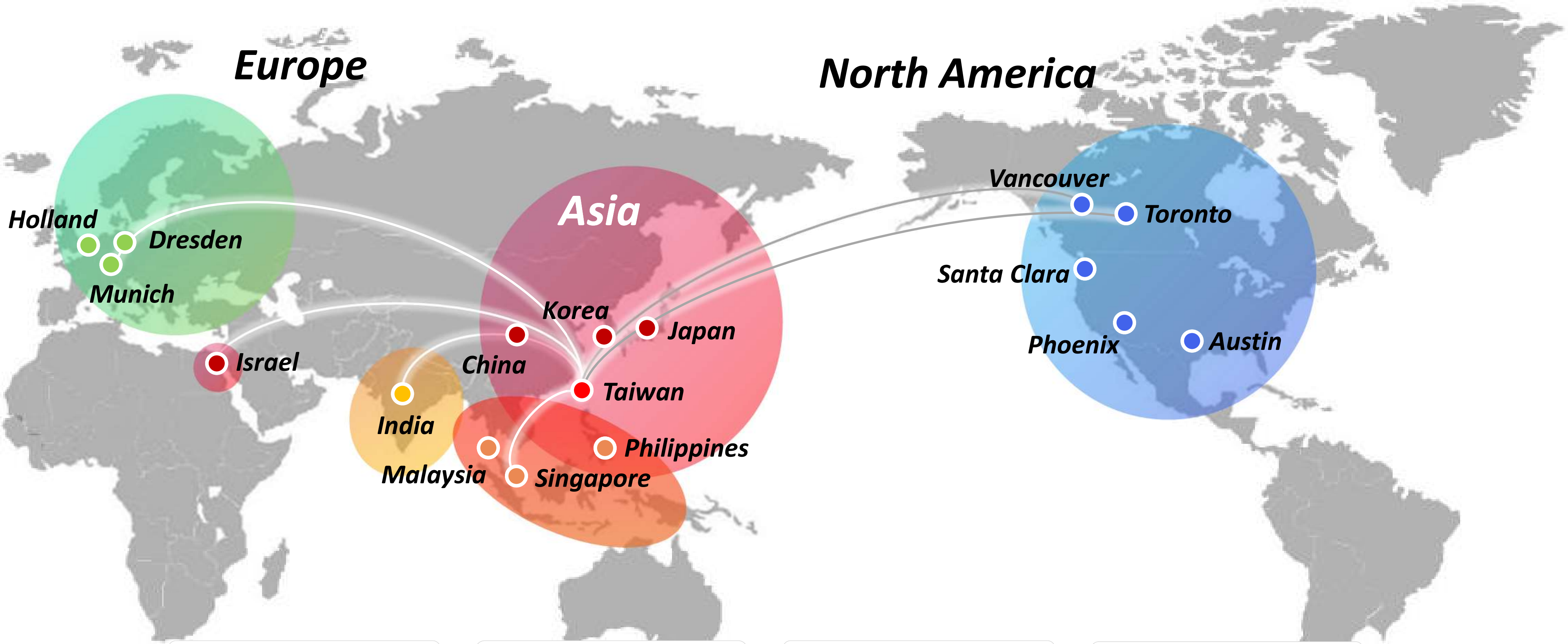
- Global Presence
- Industry Trend
- Financial Performance
- R&D Innovation

WinWay
股票代號 6515

01

Global Presence

Global Service & Support Network



KH Spring Probe

In-house spring probe

KH Plant

Coaxial Socket
HyperSocket™

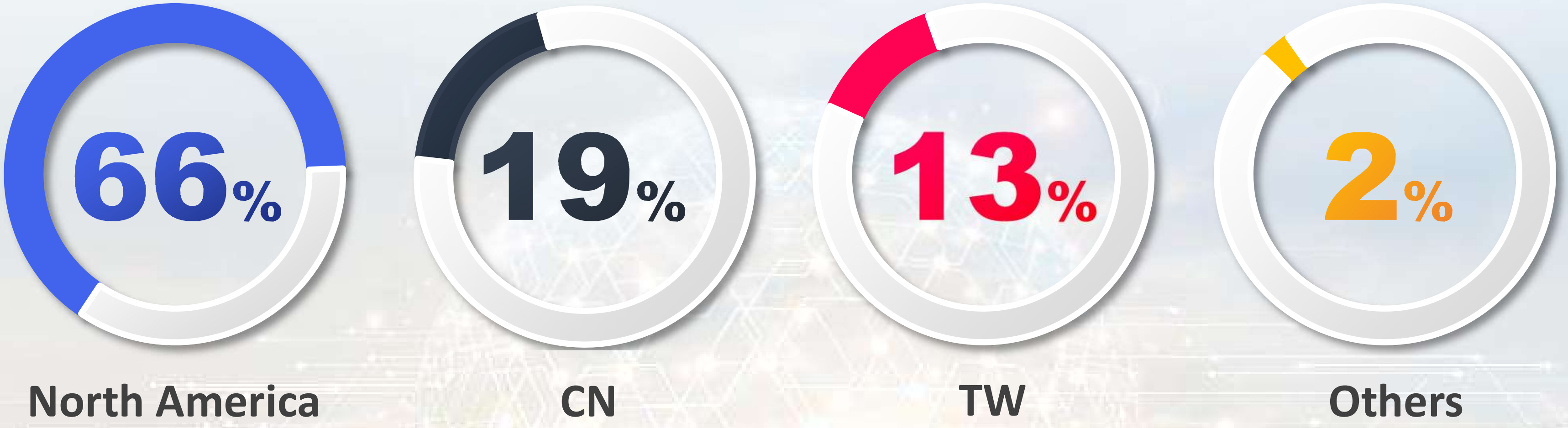
Hsinchu Plant

Vertical Probe Card

Suzhou Plant

Burn-in Socket

Worldwide Customer



83% Top10 Customers

AI
AP
HPC
CPU
IP Design
GPU

200^{+} Active Customers

- IC Design
- IDM
- CSP
- ASIC
- Foundry
- OSAT

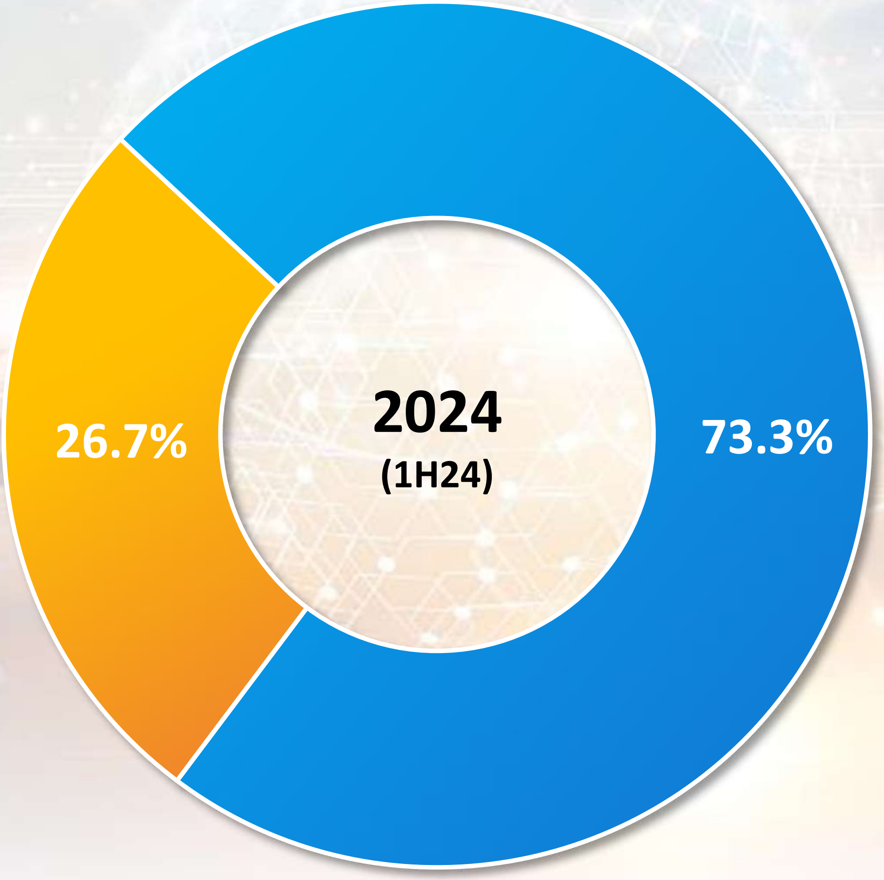
Bolstered by Advanced Technology

7nm (or equivalent node) and below

Mature Node | ***Advanced Node***

Plastic Socket | *Coaxial , HyperSocket™*

Automotive 1
Networking 2
IoT 3
DTV & STB 4
NAND Flash 5



1 *AI*
2 *HPC*
3 *GPU*
4 *CPU*
5 *Smart Phone*

WinWay
股票代號 6515

02

Industry Trend

Driving Force for AI

Data Center

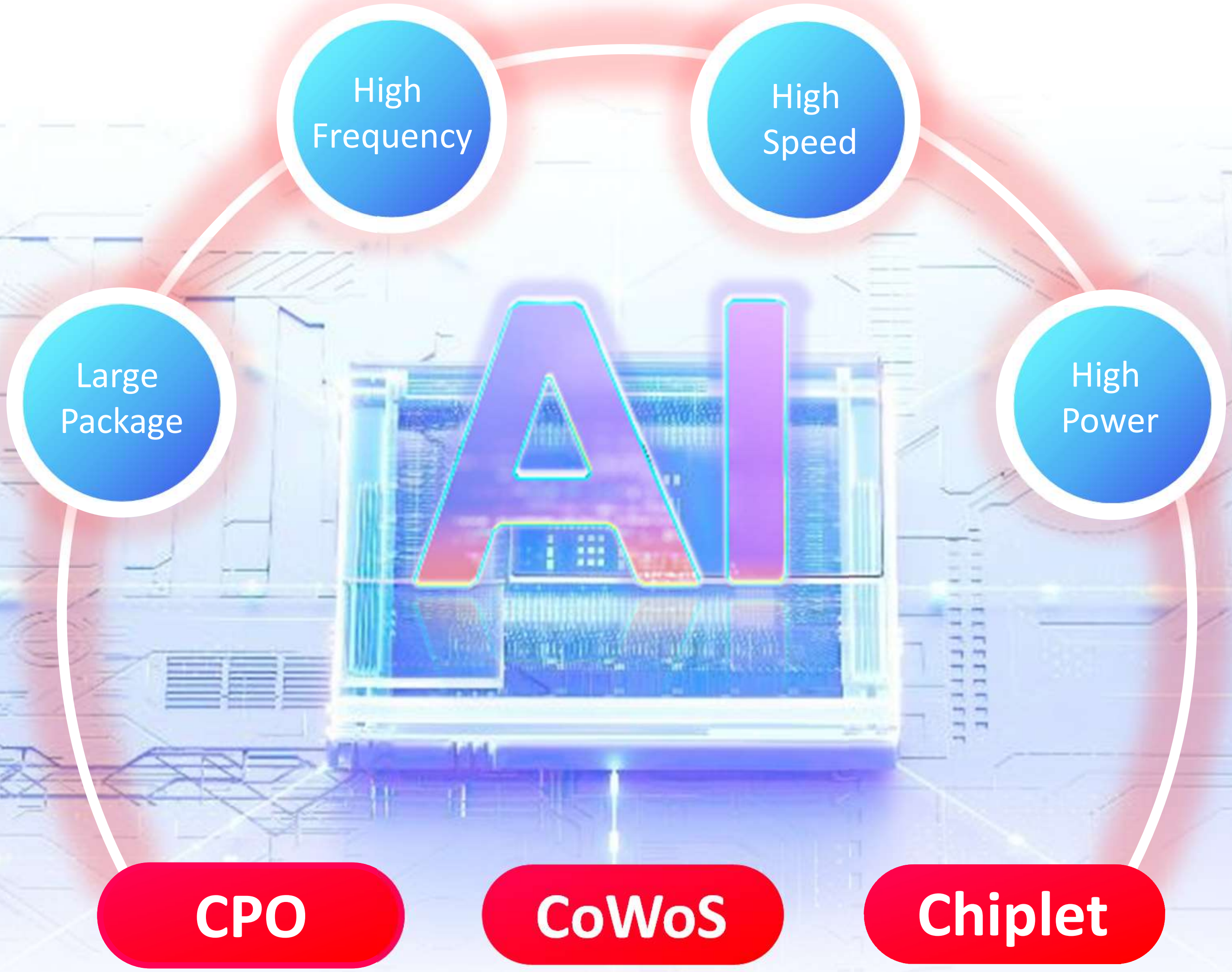
AI Server

High Speed Networking

6G Low Earth Orbit Satellite

AI PC & Phone NPU&Edge Computing

High Performance Testing Driven by Advanced Packaging



High Frequency

High Speed

Large Package

High Power

CPO

CoWoS

Chiplet

Opportunities for Semi Test Interface

Wafer Sort & Final Test

Wafer Sort (CP - Circuit Probe)

- ATE , Prober
- VPC PH
- WLCSP PC
- Load Board
- K.G.D
- CoWoS
- Chiplet
- CPO

FT (Final Test)

- ATE , Handler
- Coaxial Socket
- Plastic Socket
- Load Board
- QFP , QFN
- Flip Chip
- Package Device

DFT | Design For Testing

DFM | Design For Manufacturing

Opportunities for Semi Test Interface

SLT, SFT & Burn-in


SLT&SFT Handler


Burn-in Socket
Burn-in Board

Burn-in Oven

SLT (System Level Test) , SFT

Burn-In

- **HyperSocket™**
- Coaxial Socket
- System Board
- Interposer

- CoWoS
- Chiplet
- SiP
- Package Device

- HP BI Oven
- BI Socket
- BI Board

- Reliability BI (Static)
- Dynamic BI
- **SLT BI (Behavior)**

DFT | Design For Testing

DFM | Design For Manufacturing

Greater Need for System Level Test

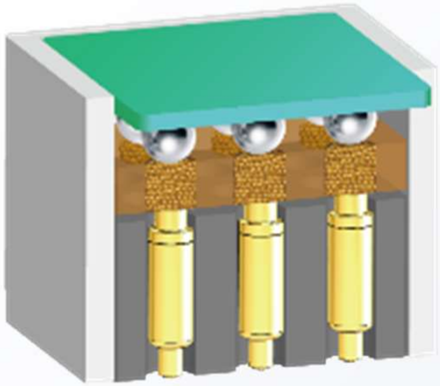
SLT&SFT

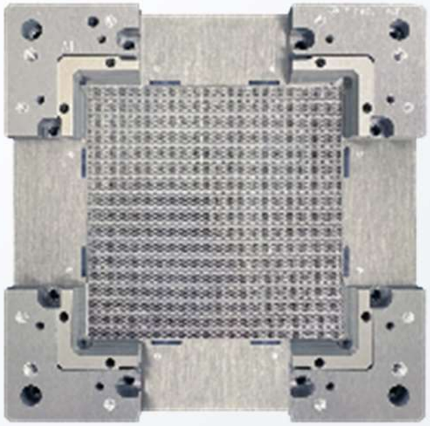
2024-2028 CAGR

More than **15%** ⬆

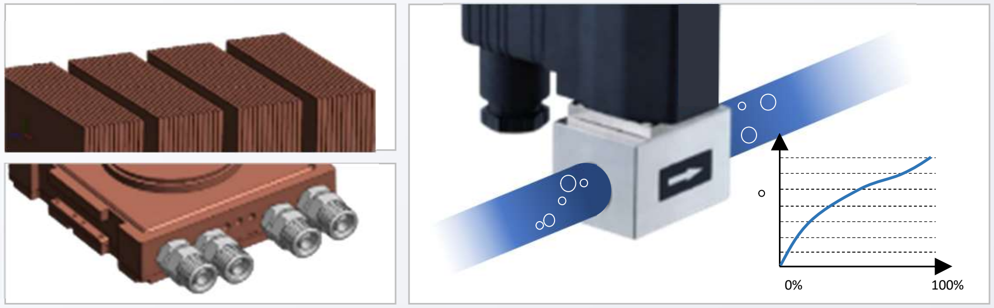
Greater than industry growth

HyperSocket™





Coaxial Socket



Thermal System (Water Cooling , Liquid Cooling)

Source: WinWay 2024

股票代號 6515

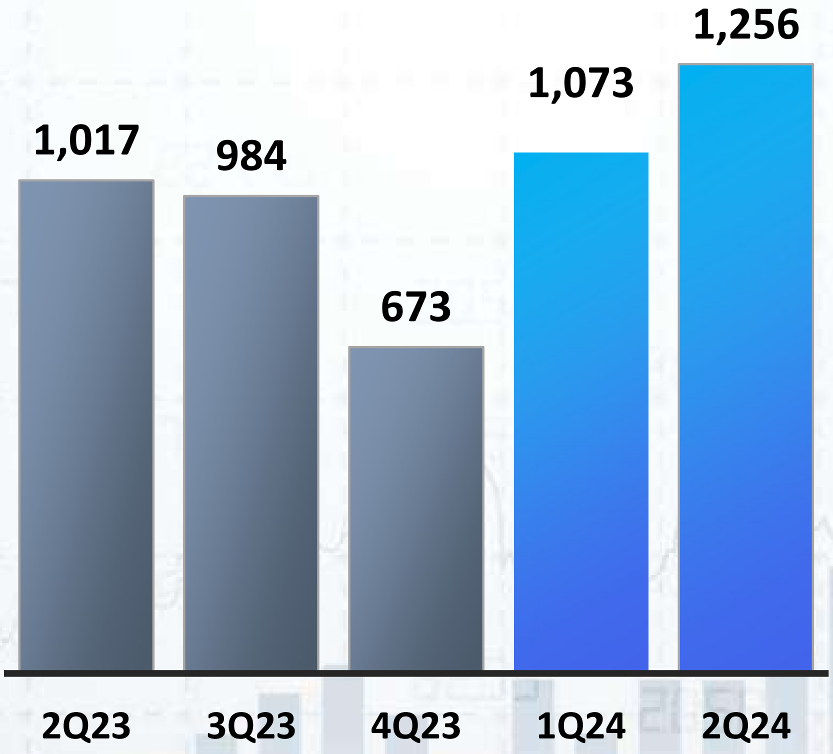
03

Financial Performance

Revenue Trend

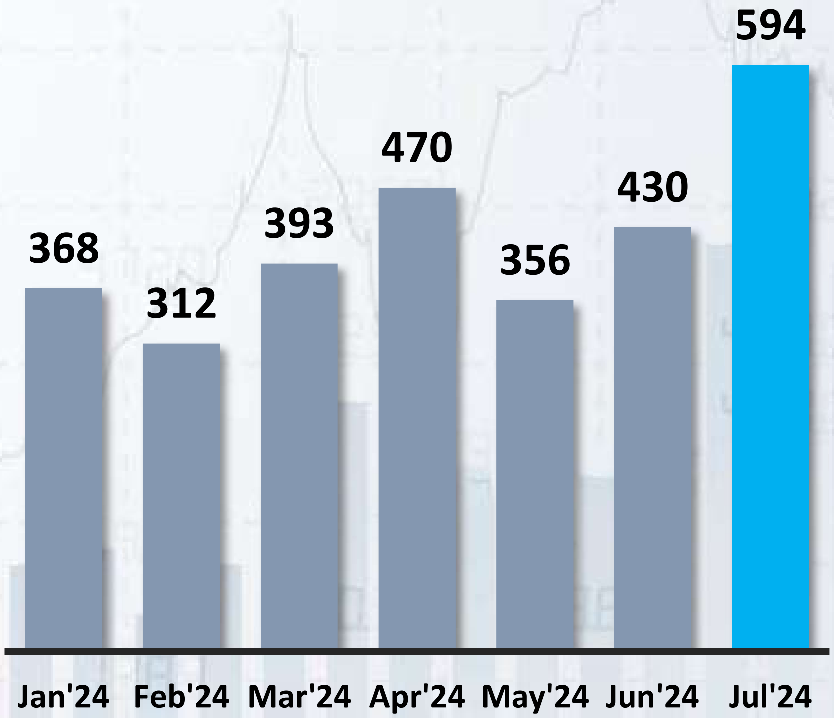
QUARTERLY REVENUE

(NTD MILLION)

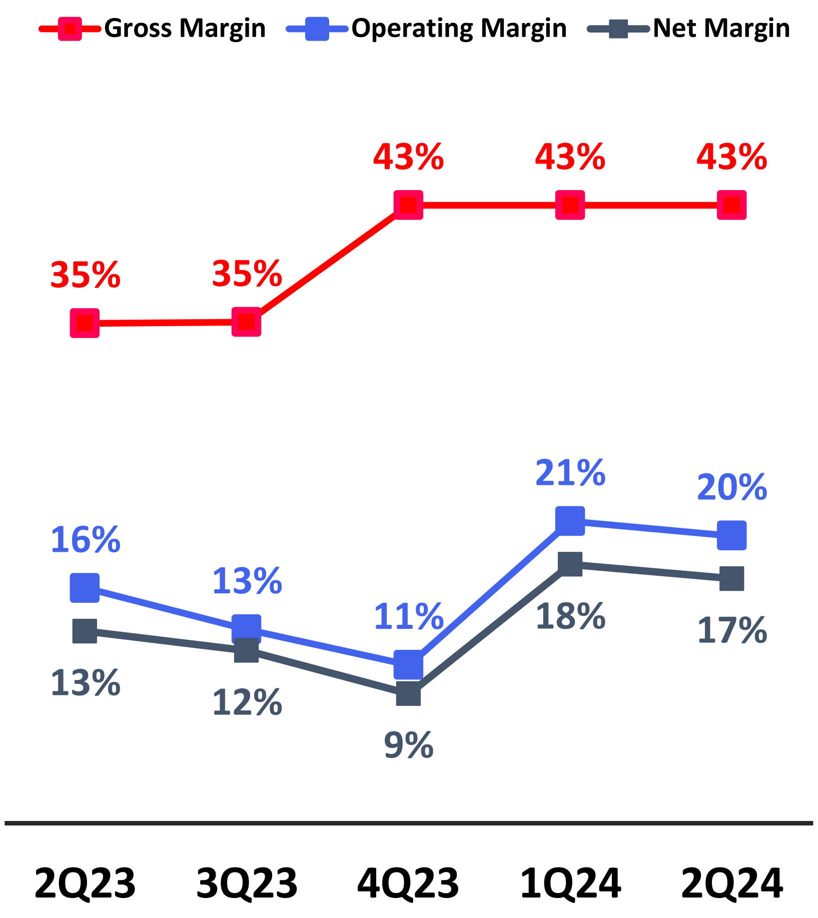


2024
MONTHLY REVENUE

(NTD MILLION)



Profitability Trend

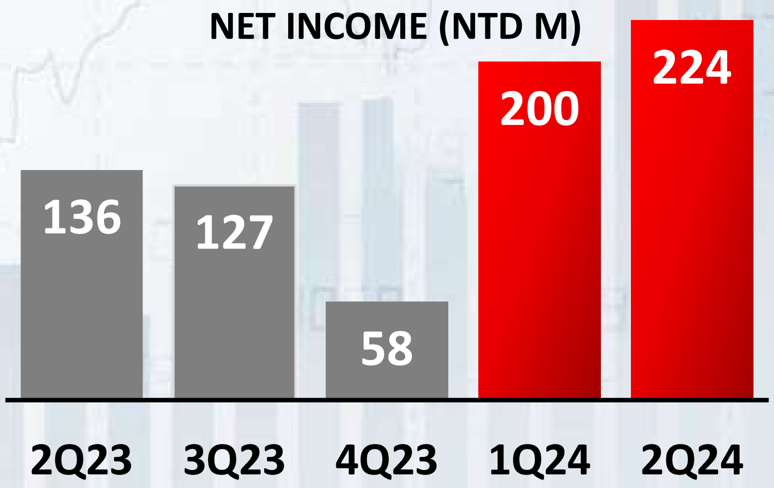


	2023 EPS	Dividend
(NT$)	13.52	11.0

Dividend Payout: 2024.08.15

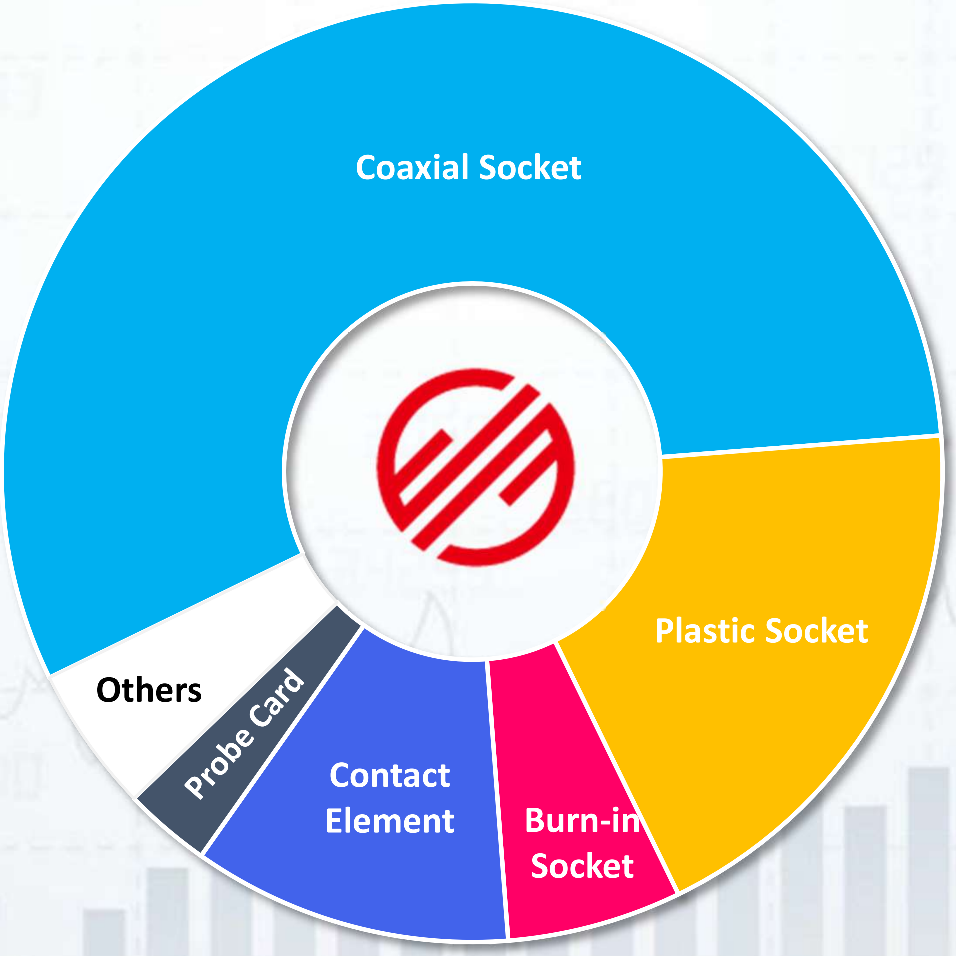
EPS (NT$)

3.96	3.70	1.68	5.81	6.52



Revenue by Product Mix

(2024.1H)



●	**Coaxial Socket**	**56%**
●	**Plastic Socket**	**19%**
●	**Contact Element**	**11%**
●	**Burn-in Socket**	**6%**
●	**Probe Card**	**3%**
○	**Others**	**5%**

Revenue by End Market

END MARKET (2024.1H)

HPC & AI

60% *HyperSocket™ , Coaxial*

PC & Gaming

12% *HyperSocket™ , Coaxial*

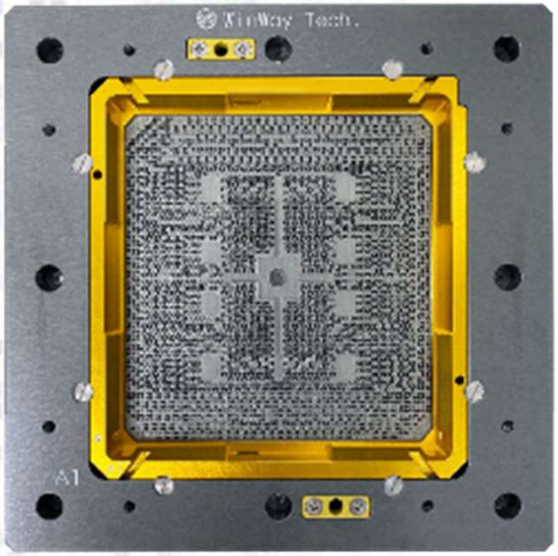
Smartphone

11% *POP Plastic Socket*

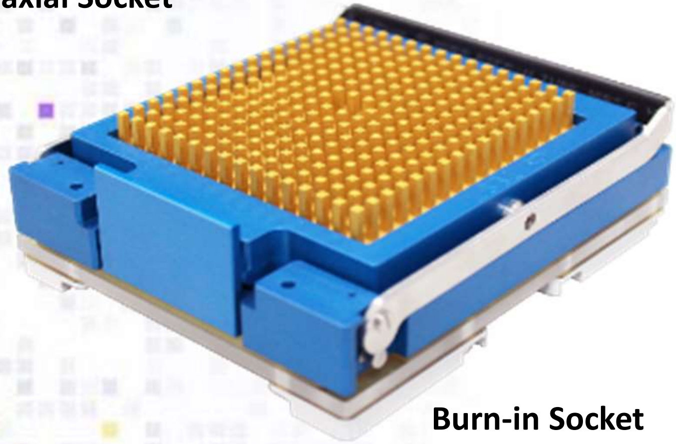
Networking & Others

17% *Plastic Socket*

Semiconductor Test Interface Leadership



Coaxial Socket



Burn-in Socket

2023
Test Socket Ranking **3**

2023
Test and Burn-in Socket Ranking **5**

2023
Probe Card Ranking **20**

Source: Yole Intelligence, 2024/04

股票代號 6515

04

R&D Innovation

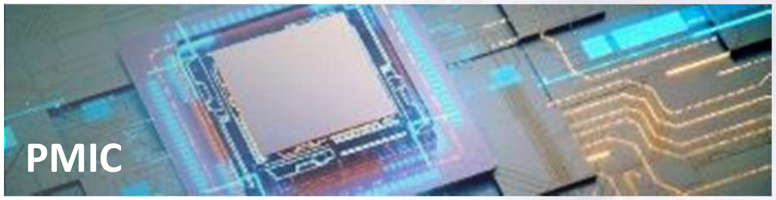
Best-in-Class Test Socket

WinWay HyperSocket™


AI , HPC SLT


Smartphone SFT


Automotive Radar


PMIC

WiFi7

Optimal for high-speed testing with outstanding consistency

Excellent thermal dissipation for probes; increased lifespan

Silicon Photonics for Co-Packaged Optics

Unlocking the Future of AI Performance

Coaxial Socket

HyperSocket™

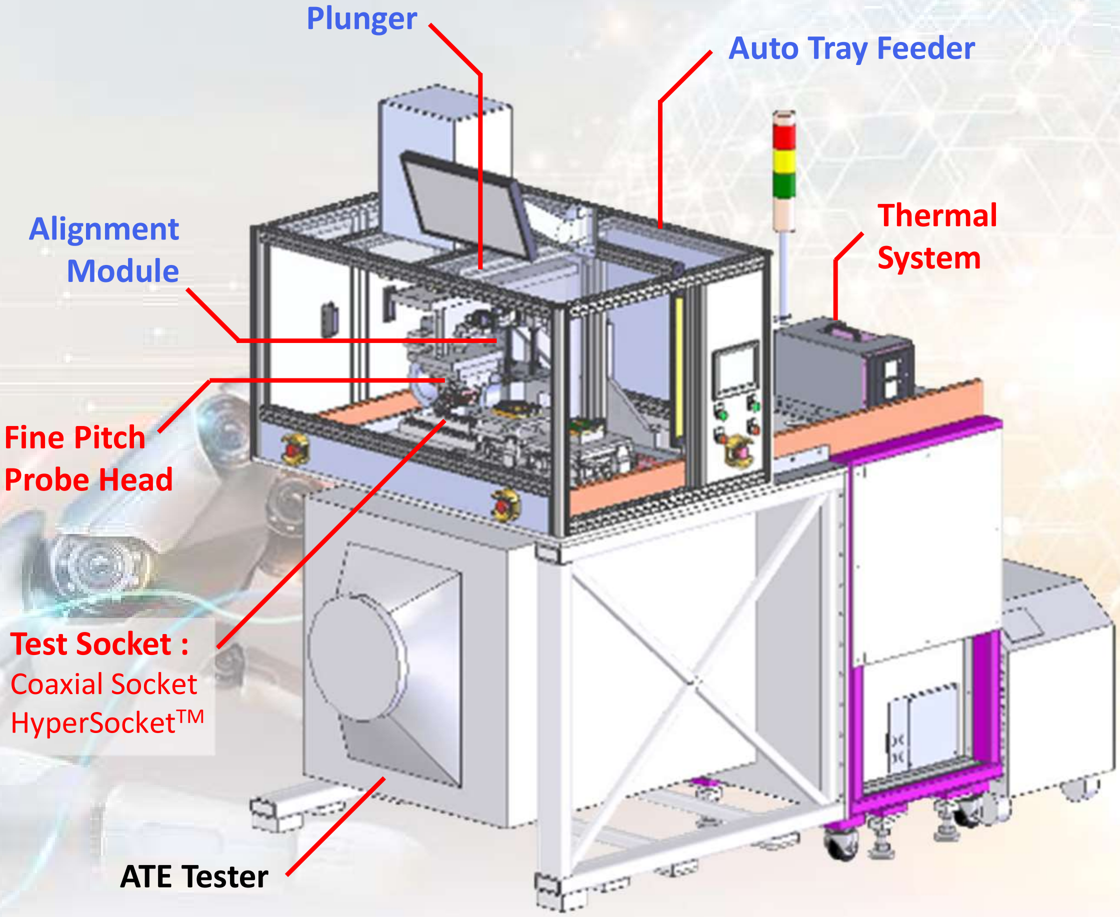
Thermal System

Vertical Probe Card

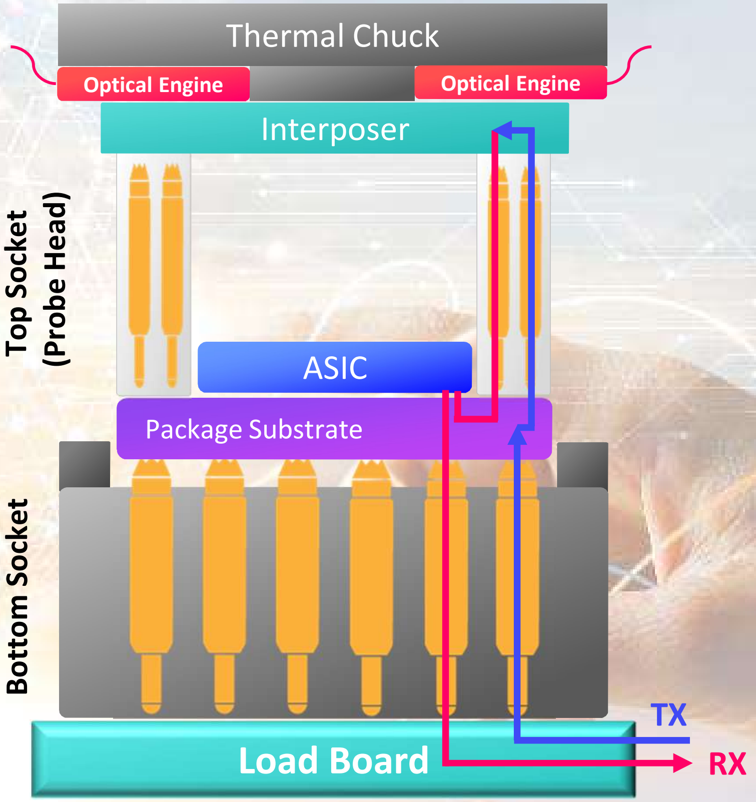
Introducing Wafer-Level CPO Probing Solution

224Gbps Optical Engine Auto Alignment System

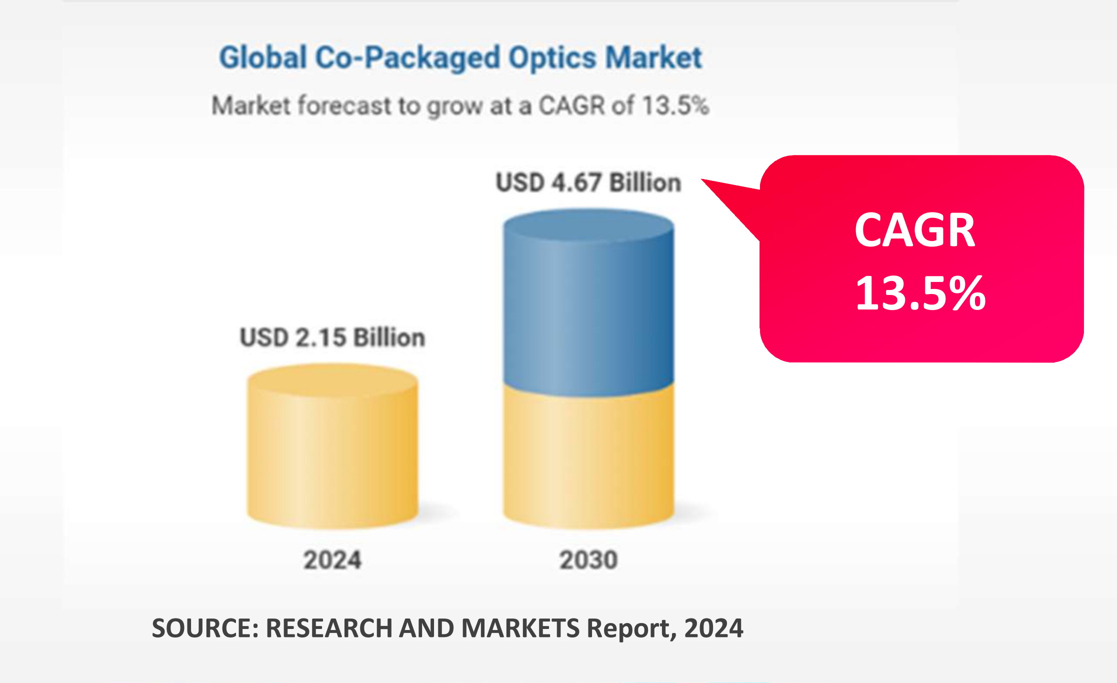
Double Sided Probing System



Optical and Electrical Test



CPO Market Opportunities



SOURCE: RESEARCH AND MARKETS Report, 2024

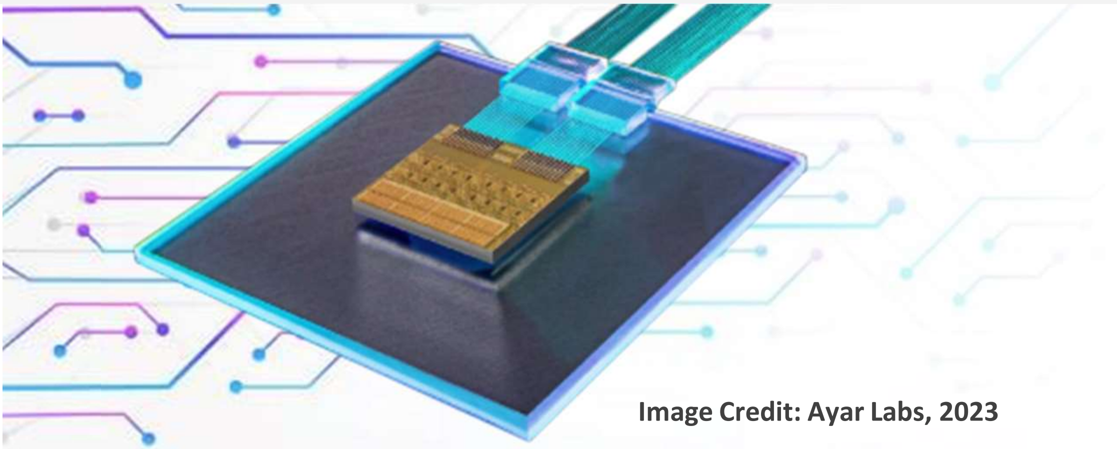


Image Credit: Ayar Labs, 2023

- **High Data Rate**
- **Lower $ per Gb/s**
- **Better Reliability**
- **Lower Power Consumption**
- **Optics and ICs are getting closer**
- **Smaller Photonics Components**

Spring Probe Manufacturing

Socket All in House

2024 Demand **6M**/ Month

2024 Capacity **3M**/ Month

2024 Output **2M**/ Month

Cost Reduction

Customer Growth

股票代號 6515

THANK YOU

You may contact WinWay Technology via

sales@winwayglobal.com

+886 7 361 0999 / +886 3 553 7632

www.winwayglobal.com